

ABSTRACT

IMPROVED APPARATUS AND METHOD FOR DISPENSING SOLDER

An apparatus for dispensing solder accurately onto a prescribed surface of a substrate including a feeding mechanism for dispensing the solid solder and a dispensing piece with a feeding channel. The positioning device has a front opening that is adapted for direct contact with the prescribed surface during the dispensing operation to form an enclosed cavity. The back opening couples the positioning device to the dispensing end of said dispensing piece such that during the dispensing operation the solder solid may be dispensed from the feeding channel through the cavity and onto the prescribed surface. The dispensing piece is maintained at a temperature below the melting temperature of the solder material such that the solder material stays in a solid state until it is in contact with the prescribed surface.

FIGURE 3